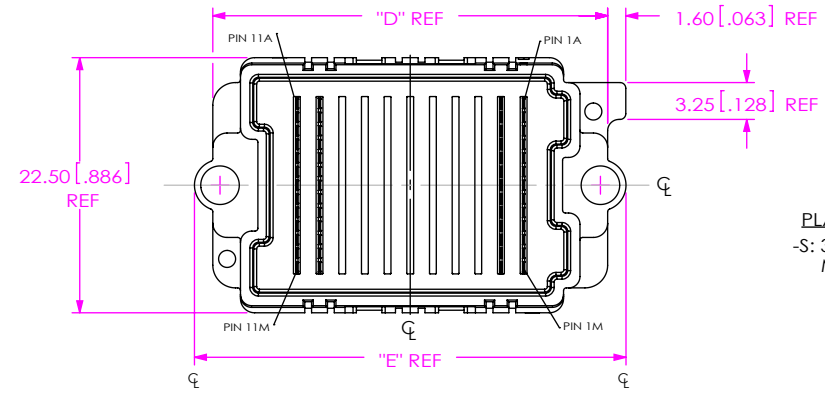


DO NOT SCALE FROM THIS PRINT

DESIGNED & DIMENSIONED IN MILLIMETERS
(INCHES FOR REFERENCE ONLY)

HDAM-XX-XX.X-X-13-X-X-XX



No OF POSITIONS
(13 ROW PER POSITION)
-11
-15
-23

LEAD STYLE
-12.0: 12MM
-17.0: 17MM

PLATING SPECIFICATION
-S: 30 μ" SELECTIVE GOLD IN MATING AREA,
MATTE TIN ON TAIL AND GUIDE PINS

No OF ROWS
-13

PACKAGING
BLANK: TRAY (SEE NOTES 6 & 7)
-TR: TAPE & REEL (SEE NOTES 7 & 8)
-FR: FULL REEL QTY TAPE & REEL
(SEE NOTES 7 & 8)

PICK & PLACE OPTION
-P: PICK & PLACE PAD
(USE MPP-26-01-N, SEE FIG 2, SHT 2)

SOLDER CHARGE MATERIAL
-1: 63%TIN / 37% LEAD
-2: 95.5% TIN / 3.8% SILVER
0.7% COPPER (LEAD FREE)

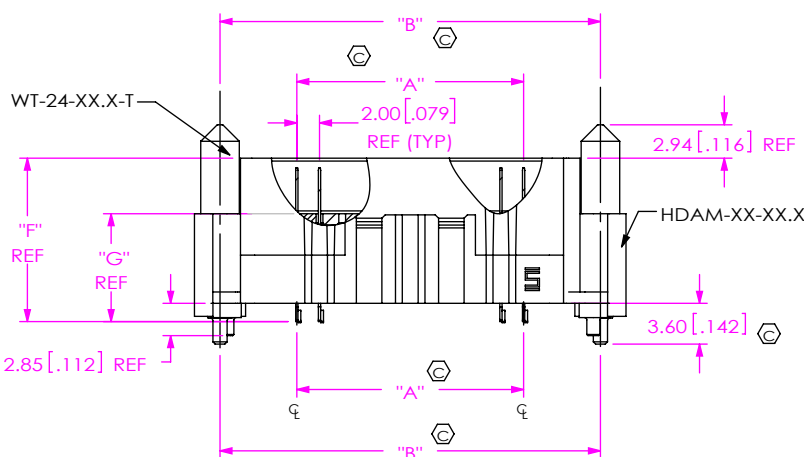


TABLE 2
STACK HEIGHT

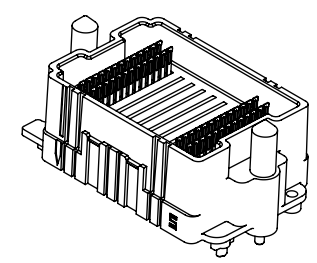
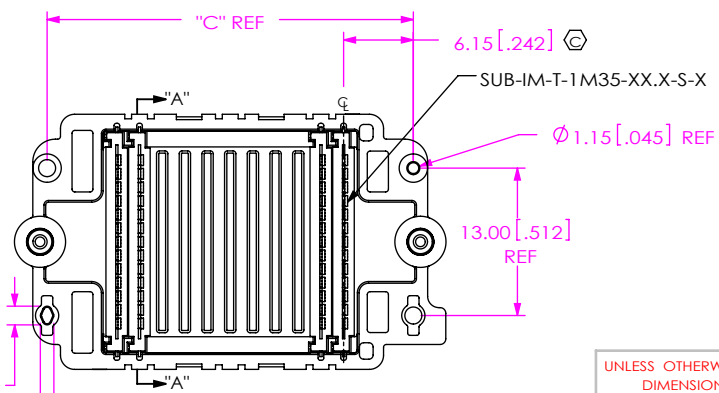
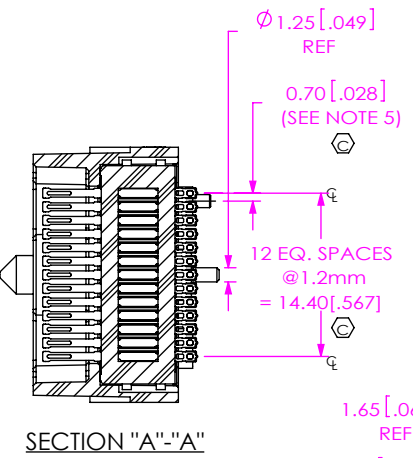
HDAM LEAD STYLE	HDAF LEAD STYLE	
	-08.0	-18.0
-12.0	20.0MM	30.0MM
-17.0	25.0MM	35.0MM

TABLE 1

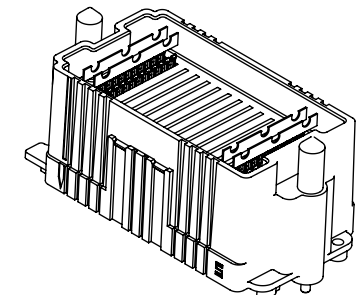
STYLE	"BODY CALLOUT"	"TERMINAL WAFER"	"GUIDE PIN"
-12.0	HDAM-XX-12.0	SUB-IM-T-1M35-12.0-S-X	WT-24-12.0-T
-17.0	HDAM-XX-17.0	SUB-IM-T-1M35-17.0-S-X	WT-24-17.0-T

TABLE 3

No. OF POS.	LEAD STYLE	"A"	"B"	"C"	"D"	"E"	"F"	"G"
11	12	20.0 [1.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	14.41 [1.567]	9.51 [1.374]
15	12	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	14.41 [1.567]	9.51 [1.374]
23	12	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.443]	14.41 [1.567]	9.51 [1.374]
11	17	20.0 [1.787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	19.41 [1.764]	14.51 [1.571]
15	17	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	19.41 [1.764]	14.51 [1.571]
23	17	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.443]	19.41 [1.764]	14.51 [1.571]



(-12.0 SHOWN)



(-17.0 SHOWN)

- NOTES:
- ⊙ REPRESENTS A CRITICAL DIMENSION.
 - MINIMUM PUSHOUT FORCE: 2.22N [0.5 LB]. FOR WAFERS
 - NOTE DELETED.
 - USE THESE SURFACES TO MEASURE "G" DIMENSION.
 - DIMENSION FROM ⌀ OF END TAIL TO ⌀ OF -A PIN.
 - TRAYS ARE STANDARD PACKAGING.
 - ORDERS WILL BE PACKAGED ACCORDING TO THE SAMTEC PACKAGING EFFICIENCY STANDARDS (SPES) FOUND ON WWW.SAMTEC.COM.
 - ATTACH LABEL TO EACH REEL.

FIG 1
-11: 11 POSITION
(HDAM-11-12.0-X-13-X-X SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS [INCHES].

TOLERANCES ARE:
DECIMALS ANGLES
X: ±0.3 [01]
.XX: ±0.13 [005]
.XXX: ±0.051 [0020]

MATERIAL: DO NOT SCALE DRAWING SHEET SCALE: 1:5.1

INSULATOR: LCP. COLOR: BLACK
CONTACT: COPPER ALLOY
WAFER MATERIAL: LCP. COLOR: BLACK
GUIDE PIN MATERIAL: BRASS
PICK AND PLACE PAD: COPPER ALLOY

PROPRIETARY NOTE
THIS DOCUMENT CONTAINS CONFIDENTIAL AND PROPRIETARY INFORMATION AND ALL DESIGN, MANUFACTURING, REPRODUCTION, USE, PATENT RIGHTS AND SALES RIGHTS ARE EXPRESSLY RESERVED BY SAMTEC, INC. THIS DOCUMENT SHALL NOT BE DISCLOSED, IN WHOLE OR PART, TO ANY UNAUTHORIZED PERSON OR ENTITY NOR REPRODUCED, TRANSFERRED OR INCORPORATED IN ANY OTHER PROJECT IN ANY MANNER WITHOUT THE EXPRESS WRITTEN CONSENT OF SAMTEC, INC.



520 PARK EAST BLVD. NEW ALBANY, IN 47150
PHONE: 812-944-6733 FAX: 812-948-5047
e-Mail info@SAMTEC.com code 55322

DESCRIPTION:
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.
HDAM-XX-XX.X-X-13-X-X-XX

BY: D KNOWLDEN 7/15/2005 SHEET 1 OF 3

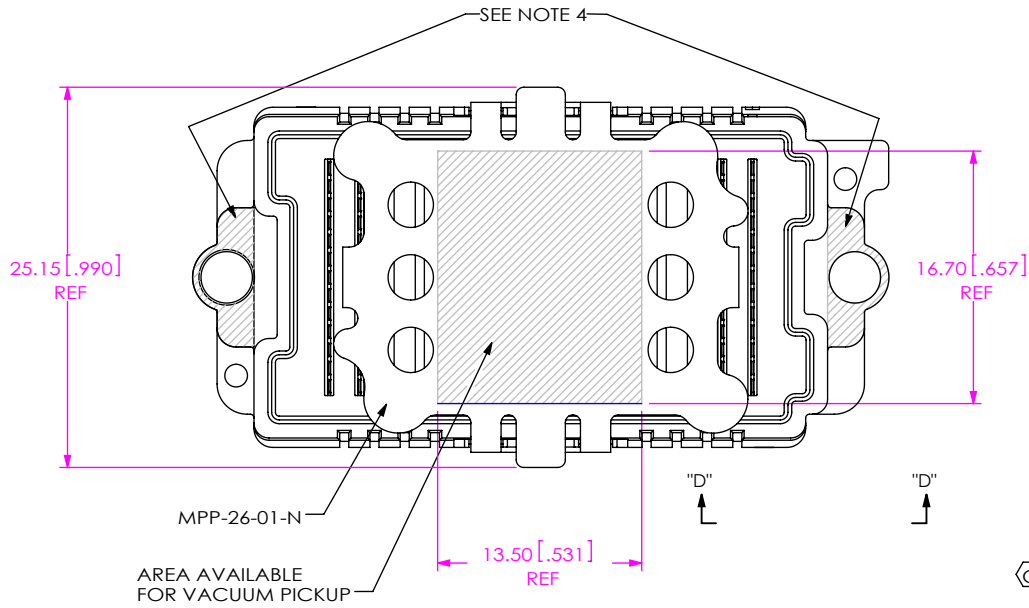
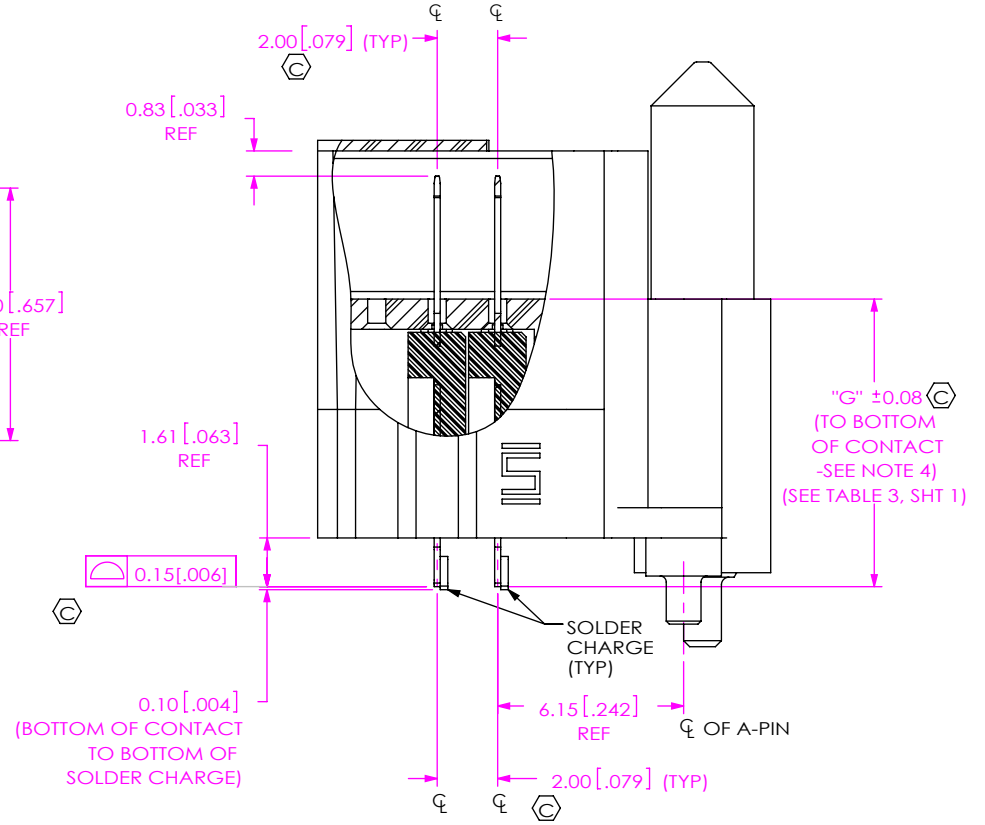
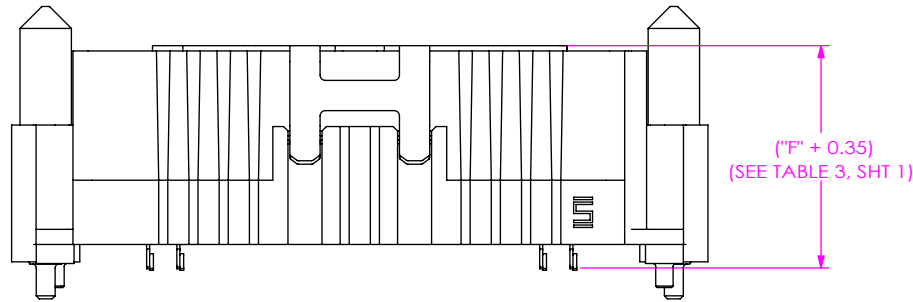


FIG 2
-15: 15 POSITION
(HDAM-15-12.0-X-13-X-P SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)



VIEW "D"-"D"
SCALE 4:1

PROPRIETARY NOTE

THIS DOCUMENT CONTAINS CONFIDENTIAL AND PROPRIETARY INFORMATION AND ALL DESIGN, MANUFACTURING, REPRODUCTION, USE, PATENT RIGHTS AND SALES RIGHTS ARE EXPRESSLY RESERVED BY SAMTEC, INC. THIS DOCUMENT SHALL NOT BE DISCLOSED, IN WHOLE OR PART, TO ANY UNAUTHORIZED PERSON OR ENTITY NOR REPRODUCED, TRANSFERRED OR INCORPORATED IN ANY OTHER PROJECT IN ANY MANNER WITHOUT THE EXPRESS WRITTEN CONSENT OF SAMTEC, INC.

DO NOT SCALE DRAWING

SHEET SCALE: 2:1

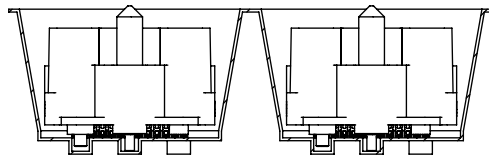
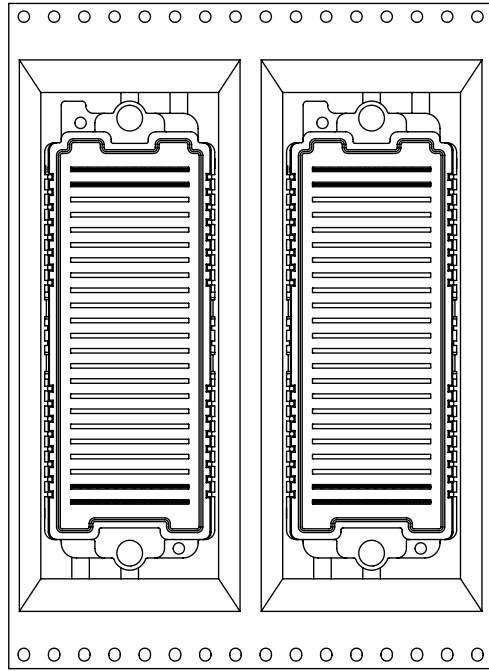


520 PARK EAST BLVD, NEW ALBANY, IN 47150
PHONE: 812-944-6733 FAX: 812-948-5047
e-Mail: info@SAMTEC.com code 55322

DESCRIPTION:
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.
HDAM-XX-XX.X-X-13-X-X-XX

BY:D KNOWLDEN 7/15/2005 SHEET 2 OF 3



USER DIRECTION OF UNREELING →
POCKET NOT DETAILED

-TR PACKAGING VIEW

PROPRIETARY NOTE
THIS DOCUMENT CONTAINS CONFIDENTIAL AND PROPRIETARY INFORMATION AND ALL DESIGN, MANUFACTURING, REPRODUCTION, USE, PATENT RIGHTS AND SALES RIGHTS ARE EXPRESSLY RESERVED BY SAMTEC, INC. THIS DOCUMENT SHALL NOT BE DISCLOSED, IN WHOLE OR PART, TO ANY UNAUTHORIZED PERSON OR ENTITY NOR REPRODUCED, TRANSFERRED OR INCORPORATED IN ANY OTHER PROJECT IN ANY MANNER WITHOUT THE EXPRESS WRITTEN CONSENT OF SAMTEC, INC.

DO NOT SCALE DRAWING

SHEET SCALE: 1:1



520 PARK EAST BLVD, NEW ALBANY, IN 47150
PHONE: 812-944-6733 FAX: 812-948-5047
e-Mail info@SAMTEC.com code 55322

DESCRIPTION:
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.
HDAM-XX-XX.X-X-13-X-X-XX

BY: D KNOWLDEN 7/15/2005 SHEET 3 OF 3